


PCN Number:	20230919000.1		PCN Date:	September 19, 2023	
Title:	Qualification of RFAB as an additional Fab site option for select HPA07 devices				
Customer Contact:	Change Management team		Dept:	Quality Services	
Proposed 1st Ship Date:	Dec 19, 2023		Sample requests accepted until:	October 19, 2023*	
*Sample requests received after October 19, 2023 will not be supported.					
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the addition of RFAB as an additional Wafer Fab site option for the products listed in the "Product Affected" section of this document.					
Current Fab Site			New Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
DP1DM5	HPA07	200mm	RFAB	HPA07	300mm
Qual details are provided in the Qual Data Section.					
Reason for Change:					
Continuity of supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Fab Site Information:					
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
DP1DM5	DM5	USA	Dallas		
RFAB	RFB	USA	Richardson		
Sample product shipping label (not actual product label)					
					
Product Affected:					
ADS131E04IPAG	ADS131E06IPAG	ADS131E08IPAG			
ADS131E04IPAGR	ADS131E06IPAGR	ADS131E08IPAGR			

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: ADS131E08IPAGR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: CD3232A1YFFR	QBS Process Reference: AMC7836IPAP	QBS Process Reference: INA231AIYFDR	QBS Process Reference: INA231BIYFDR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	3/231/0	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	3/231/0	-	1/77/0	2/154/0
HTOL	B1	Life Test	140C	480 Hours	-	1/77/0	2/154/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	1/77/0	1/77/0	2/154/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	1/1000/0	2/2000/0	-	1/1000/0	2/2000/0
ESD	E2	ESD CDM	-	1000 Volts	-	-	-	1/3/0	-	-
ESD	E2	ESD CDM	-	200 Volts	-	-	3/9/0	-	-	-
ESD	E2	ESD CDM	-	500 Volts	1/3/0	-	-	-	-	2/6/0
ESD	E2	ESD CDM	-	350 Volts	-	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	3/9/0	3/9/0	-	-	2/6/0
ESD	E2	ESD HBM	-	2500 Volts	-	-	-	1/3/0	-	-
ESD	E2	ESD HBM	-	1500 Volts	-	-	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	3/9/0	3/9/0	1/3/0	1/6/0	2/12/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	2/60/0
FTY	E6	Final Test Yield	-	-	1/Pass	-	-	-	-	-

- QBS: Qual By Similarity
- Qual Device ADS131E08IPAGR is qualified at MSL3 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-NPD-2211-033

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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